L Number	Hits		DB	Time stamp
_	46	emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8	USPAT; US-PGPUB;	2004/01/27 09:34
			EPO; JPO; DERWENT; IBM TDB	
-	15	emboss\$3 near (die tool stamp) and (high adj aspect) and electrodep\$10	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 09:36
-	12	emboss\$3 near (die tool stamp) and (high adj aspect) and electrolyt\$10	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 09:36
-	46	<pre>(emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) (emboss\$3 near (die tool stamp) and (high adj aspect) and electrodep\$10) (emboss\$3 near (die tool stamp) and (high adj aspect) and electrolyt\$10)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 09:51
-	1 1	(US-20030038105-\$).did. ((US-20030038105-\$).did.) and high	US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 09:51 2004/01/27 09:51
-	8	(US-6422528-\$ or US-6284072-\$ or US-5575878-\$ or US-5279689-\$).did. or (US-20020179449-\$ or US-20010041307-\$).did. or (US-6350360-\$).did. or (NN8607532).tban.	USPAT; US-PGPUB; DERWENT; IBM TDB	2004/01/27 10:28
-	6	((US-6422528-\$ or US-6284072-\$ or US-5575878-\$ or US-5279689-\$).did. or (US-20020179449-\$ or US-20010041307-\$).did. or (US-6350360-\$).did. or (NN8607532).tban.)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 10:29
-	6	and etch\$3 (((US-6422528-\$ or US-6284072-\$ or US-5575878-\$ or US-5279689-\$).did. or (US-20020179449-\$ or US-20010041307-\$).did. or (US-6350360-\$).did. or (NN8607532).tban.) and etch\$3) and ratio	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 10:29
-	1	(((US-6422528-\$ or US-6284072-\$ or US-5575878-\$ or US-5279689-\$).did. or (US-20020179449-\$ or US-20010041307-\$).did. or (US-6350360-\$).did. or (NN8607532).tban.)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 10:30
	6	and etch\$3) and ratio near "1" (((US-6422528-\$ or US-6284072-\$ or US-5575878-\$ or US-5279689-\$).did. or (US-20020179449-\$ or US-20010041307-\$).did. or (US-6350360-\$).did. or (NN8607532).tban.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 11:29
	7	and etch\$3) and high adj aspect adj ratio (emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and pointed	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 11:30
-	5	(emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and obelisk	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 11:29
-	7	((emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and pointed) ((emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and obelisk)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/27 11:30
	13	(emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and (sharp conical needle needle-like)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 11:44

			•	
_	1.8	(((emboss\$3 near (die tool stamp) and (high	USPAT;	2004/01/27 11:31
•		adj aspect) and electro\$8) and pointed)	US-PGPUB;	
		((emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and obelisk))	EPO; JPO; DERWENT;	
		((emboss\$3 near (die tool stamp) and (high	IBM TDB	·
		adj aspect) and electro\$8) and (sharp	12122	
		conical needle needle-like))		
_	o	((US-6422528-\$ or US-6284072-\$ or	USPAT;	2004/01/27 11:32
		US-5575878-\$ or US-5279689-\$).did. or	US-PGPUB;	
		(US-20020179449-\$ or US-20010041307-\$).did.	EPO; JPO;	
		or (US-6350360-\$).did. or (NN8607532).tban.)	DERWENT;	
		AND ((((emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and	IBM_TDB	
	:	pointed) ((emboss\$3 near (die tool stamp)		
		and (high adj aspect) and electro\$8) and		
		obelisk)) ((emboss\$3 near (die tool stamp)		
		and (high adj aspect) and electro\$8) and		
		(sharp conical needle needle-like)))		
-	12	(emboss\$3 near (die tool stamp) and (high	USPAT;	2004/01/27 11:44
		adj aspect) and electro\$8) and pyramid\$3	US-PGPUB;	
			EPO; JPO; DERWENT;	
	-		IBM TDB	· .
_	17	(emboss\$3 near (die tool stamp) and (high	USPAT;	2004/01/27 11:44
		adj aspect) and electro\$8) and ridges	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		//omboggt2 moon /dia tool stame\ and /bish	IBM_TDB USPAT;	2004/01/27 11:52
_	25	((emboss\$3 near (die tool stamp) and (high adj aspect) and electro\$8) and pyramid\$3)	US-PGPUB;	2004/01/2/ 11:52
		((emboss\$3 near (die tool stamp) and (high	EPO; JPO;	·
		adj aspect) and electro\$8) and ridges)	DERWENT;	
			IBM_TDB	
_	0	emboss and perot	USPAT;	2004/01/27 11:52
		·	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	56	emboss\$3 and (fabry adj perot fabry-perot)	USPAT;	2004/01/27 12:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
:	59	emboss\$3 and perot	IBM_TDB USPAT;	2004/01/27 12:23
_	, 59	emboss33 and peroc	US-PGPUB;	2004,01,2, 12.23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	672	emboss\$3 and fresnel	USPAT;	2004/01/27 12:24
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	125	emboss\$3 with fresnel	USPAT;	2004/01/27 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	9	ombogg\$3 near fregnel	<pre>IBM_TDB USPAT;</pre>	2004/01/27 12:28
-	9	emboss\$3 near fresnel	US-PGPUB;	2004/01/2/ 12:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	emboss\$3 near microneedle	USPAT;	2004/01/27 12:29
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
L	1			

-	2	emboss\$3 near microneedle and (si silicon)	USPAT; US-PGPUB; EPO; JPO;	2004/01/27 12:30
	•		DERWENT; IBM TDB	
_	1.1	emboss\$3 with microneedle and (si silicon)	USPAT; US-PGPUB;	2004/01/27 12:30
			EPO; JPO;	
			DERWENT; IBM_TDB	
	98	high adj aspect and emboss\$3 and (electroplat\$3 electroform\$3)	USPAT; US-PGPUB;	2004/02/12 16:07
			EPO; JPO; DERWENT;	
	3	high adj aspect with emboss\$3 with	IBM_TDB USPAT;	2004/02/12 16:08
_		(electroplat\$3 electroform\$3)	US-PGPUB; EPO; JPO;	
			DERWENT;	
_	0	20030038105.URPN.	IBM_TDB USPAT	2004/02/12 16:08
	1	2003-418127.NRAN.	DERWENT	2004/02/12 16:08
_	6	high adj aspect with emboss\$3 same (electroplat\$3 electroform\$3) not (high adj	USPAT; US-PGPUB;	2004/02/13 14:19
		aspect with emboss\$3 with (electroplat\$3	EPO; JPO;	
		electroform\$3))	DERWENT;	
_	0	(metal metallic) near die with emboss\$3 same	IBM_TDB USPAT;	2004/02/13 14:21
		((high adj aspect) "5:1")	US-PGPUB;	
		·	EPO; JPO; DERWENT;	
			IBM_TDB	
-	0	(metal metallic) with die with emboss\$3 same ((high adj aspect) "5:1")	USPAT; US-PGPUB;	2004/02/13 14:21
		((J)	EPO; JPO;	
		·	DERWENT; IBM_TDB	
-	475	(metal metallic) with die with emboss\$3	USPAT; US-PGPUB;	2004/02/13 14:21
			EPO; JPO;	
			DERWENT; IBM TDB	,
_	80	(metal metallic) near die with emboss\$3	USPAT; US-PGPUB;	2004/02/13 14:22
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	(metal metallic) near die with emboss\$3 same	USPAT;	2004/02/13 14:22
		ratio	US-PGPUB; EPO; JPO;	
			DERWENT;	
_	٦	(metal metallic) near die with emboss\$3 and	IBM_TDB USPAT;	2004/02/13 14:22
		aspect adj ratio	US-PGPUB;	
			EPO; JPO; DERWENT;	
		/motol metallial many dia with embarate and	IBM_TDB USPAT;	2004/02/13 14:30
_	26	(metal metallic) near die with emboss\$3 and ratio	US-PGPUB;	2004/02/13 14.30
			EPO; JPO; DERWENT;	
			IBM_TDB	
_	0	20030187170.URPN.	USPAT;	2004/02/13 14:28 2004/02/13 14:35
_	27	(metal metallic) with die with emboss\$3 and aspect adj ratio	US-PGPUB;	2004/02/13 14.33
			EPO; JPO; DERWENT;	
			IBM_TDB	

((metal metallic) near die with emboss\$3) not ((metal metallic) near die with emboss\$3 and ratio) ((metal metallic) near die with emboss\$3 and aspect adj ratio) ((metal metallic) with die with emboss\$3 and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 14:35
aspect adj ratio))		